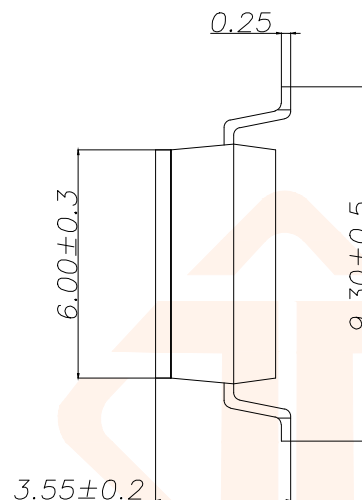
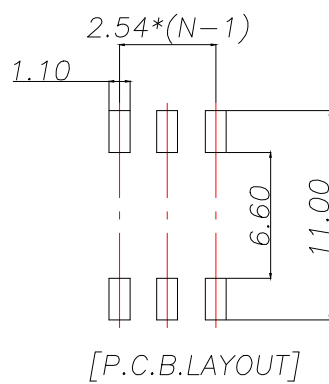
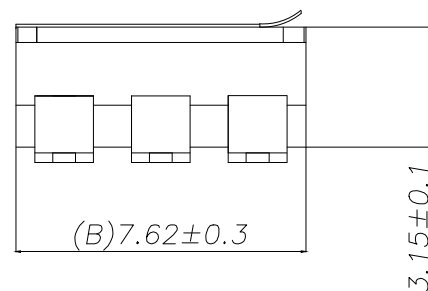
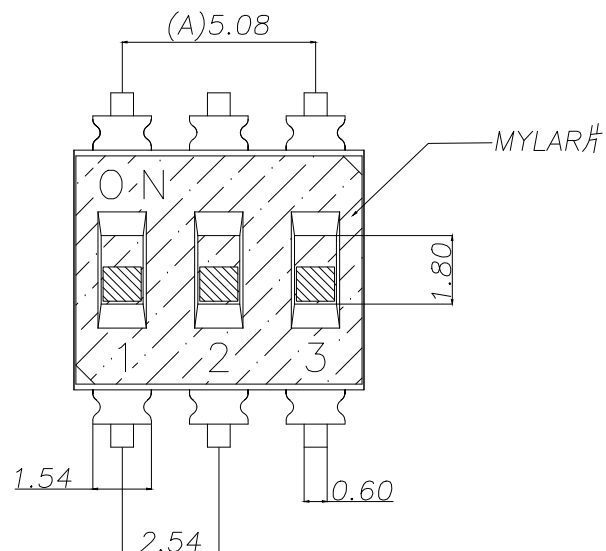


[Schematic]

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

NOTES:

1.Specification:

- 1>.Operation force: 1000gf Max.
- 2>.Operation Temperature: -30°C to $+85^{\circ}\text{C}$.
- 3>.Storage Temperature: -40°C to $+85^{\circ}\text{C}$.
- 4>.Mechanical Life: 3000 cycles operations.
- 5>.Resistance to Soldering: $260\pm 5^{\circ}\text{C}$ for 3-5 Seconds.

2.PLATING:

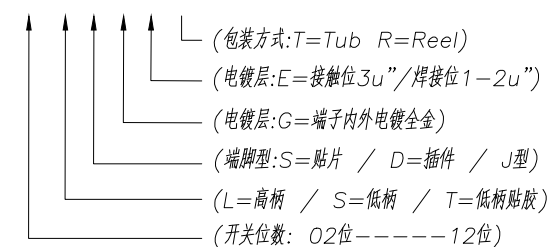
- 1>.GOLD flash 1u"(min) SOLDERTAIL,
3u" GOLD PLATING ON THE CONTACT AREA.

3.ELECTRICAL:

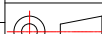
- 1>.Non-switch Rating: 100mA at 50V DC.
- 2>.Switching Rating: 25mA at 24V DC.
- 3>.Contact Resistance: Initial 50m Ω Max.
Contact Resistance: After life 100m Ω Max.
- 4>.Insulation Resistance: 100M Ω Min at 500VDC.
- 5>.Dielectric Strength: 500V AC for 60seconds.
- 6>.Switch Capacitance: 5PF Max at 1MHZ.

4.PART NUMBER DESCRIPTION:

DSIC XX I S G E R



5.PACKING: 1000pcs/REEL.

TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd			
>0±0.05	>0°±0.5°	PART NO. DSIC03TSGER	TITLE:PRODUCT Family DSIC Series Pitch 2.54mm		
>1±0.10	>5°±1.0°				
>10±0.30					
UNITS	mm	DESIGN: Ethan	MANUFACTURE DWG		
MATERILA	— — —	CHED: Olvia			
FINISH	— — —	APPD: Ava		SCALE N:A	SHEET 1/1